

N-Ch 100V Fast Switching MOSFETs

Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

Product Summary

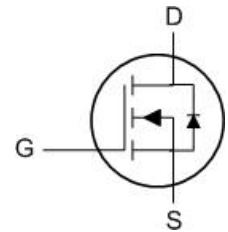
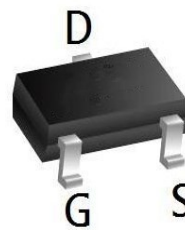


BVDSS	RDSON	ID
100V	63mΩ	8A

Applications

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

SOT23-3L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	8	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	5	A
I_{DM}	Pulsed Drain Current ²	50	A
EAS	Single Pulse Avalanche Energy ³	22	mJ
I_{AS}	Avalanche Current	---	A
$P_D@T_C=25^\circ C$	Total Power Dissipation ⁴	8	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	---	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	---	$^\circ C/W$

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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	100	---	---	V
ΔBV _{DSS} /ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =1mA	---	---	---	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =5A	---	63	78	mΩ
		V _{GS} =4.5V, I _D =4A	---	79	98	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.3	1.8	2.3	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	---	---	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =100V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =100V, V _{GS} =0V, T _J =100°C	---	---	100	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =5A	---	---	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	---	---	Ω
Q _g	Total Gate Charge	V _{DS} =50V, V _{GS} =10V, I _D =5A	---	3.7	---	nC
Q _{gs}	Gate-Source Charge		---	0.8	---	
Q _{gd}	Gate-Drain Charge		---	1	---	
T _{d(on)}	Turn-On Delay Time	V _{GS} =10V, V _{DD} =50V, R _G =3Ω, I _D =5A	---	8	---	ns
T _r	Rise Time		---	16	---	
T _{d(off)}	Turn-Off Delay Time		---	17	---	
T _f	Fall Time		---	14	---	
C _{iss}	Input Capacitance	V _{DS} =50V, V _{GS} =0V, f=1MHz	---	228	---	pF
C _{oss}	Output Capacitance		---	58	---	
C _{rss}	Reverse Transfer Capacitance		---	1.9	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,4}	V _G =V _D =0V, Force Current	---	---	8	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =8A, T _J =25°C	---	---	1.2	V
t _{rr}	Reverse Recovery Time	I _F =8A, di/dt=100A/μs, T _J =25°C	---	22	---	nS
Q _{rr}	Reverse Recovery Charge		---	18	---	nC

Note :

F The data is tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

G The data is tested by pulsed pulse width ≤ 300us duty cycle ≤ 2%

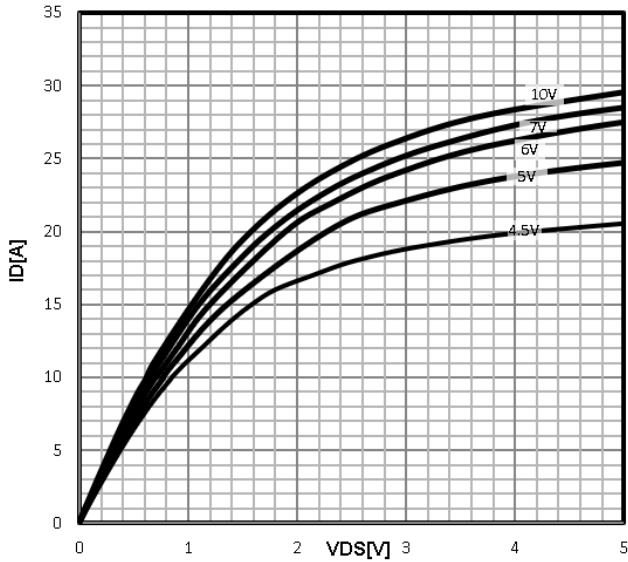
H The EAS data shows Max. rating. The test condition is V_{RMS} × 0, V_{DD}=50V, V_{GS}=10V, L=5mH.

I The power dissipation is limited by 150°C junction temperature

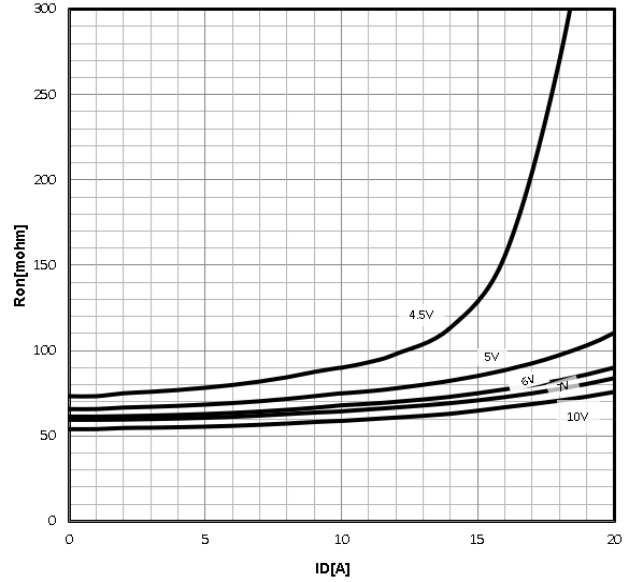
J The data is theoretically the same as A_{DM} and A_{DM} in real applications should be limited by total power dissipation.

Characteristics Curve:

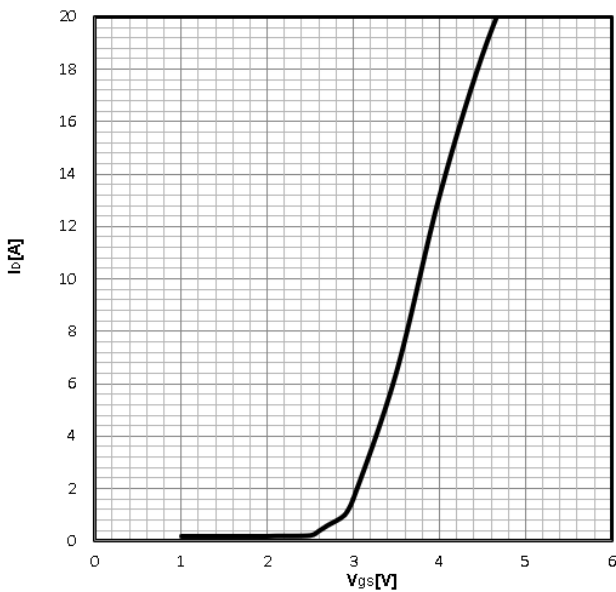
Typ. output characteristics
 $I_D=f(V_{DS})$



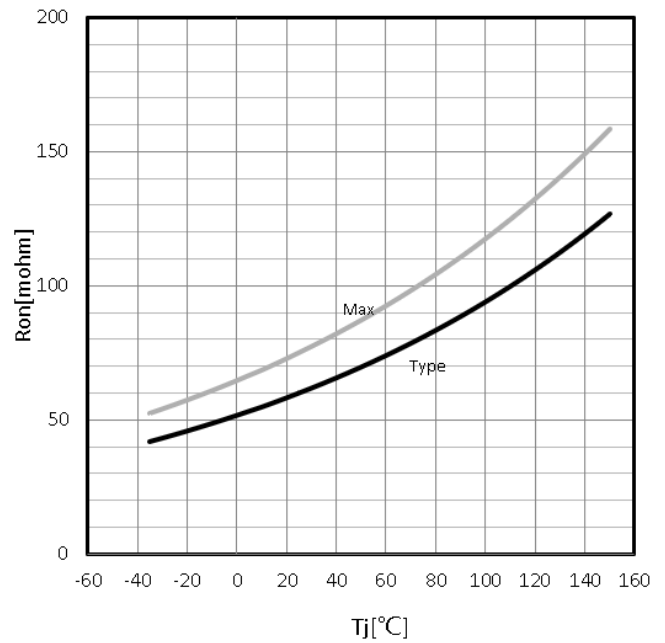
Typ. drain-source on resistance
 $R_{DS(on)}=f(I_D)$



Typ. transfer characteristics
 $I_D=f(V_{GS})$



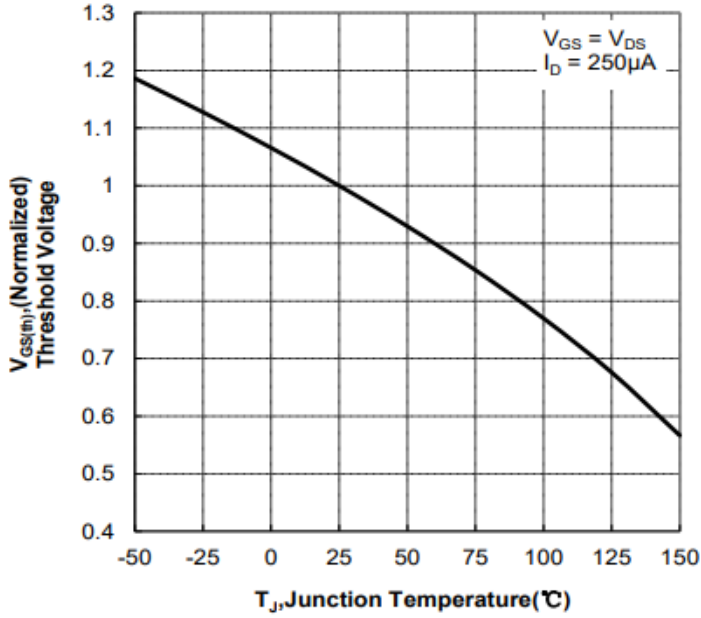
Drain-source on-state resistance
 $R_{DS(on)}=f(T_j); I_D=5A; V_{GS}=10V$



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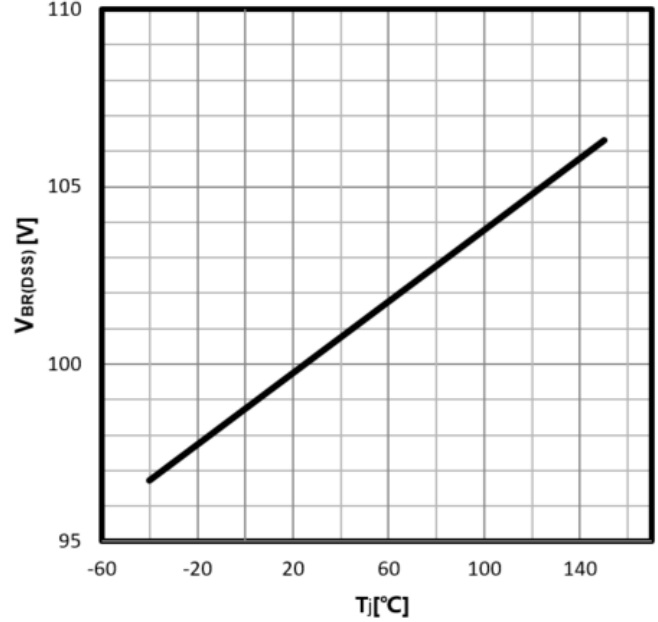
Gate Threshold Voltage

$V_{TH}=f(T_j); I_D=250\mu A$



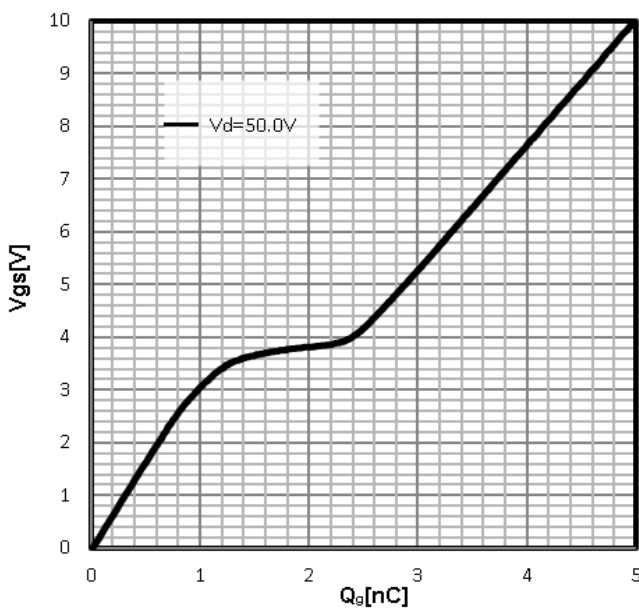
Drain-source breakdown voltage

$V_{BR(DSS)}=f(T_j); I_D=250\mu A$



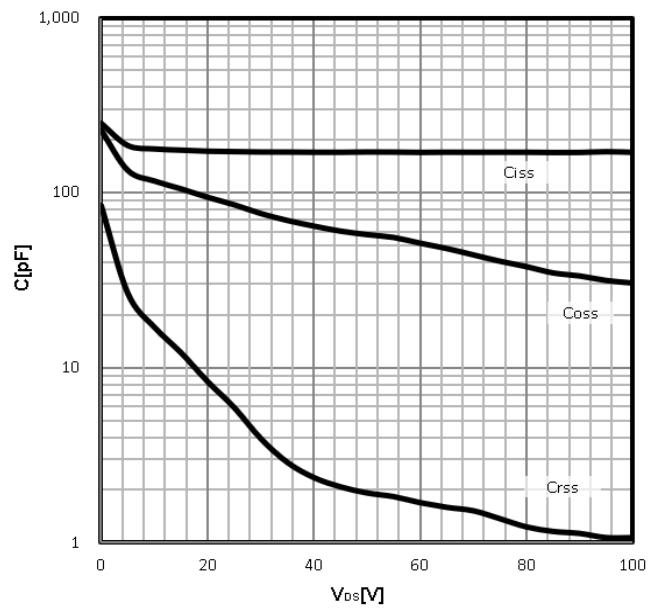
Typ. gate charge

$V_{GS}=f(Q_g); I_D=10A$

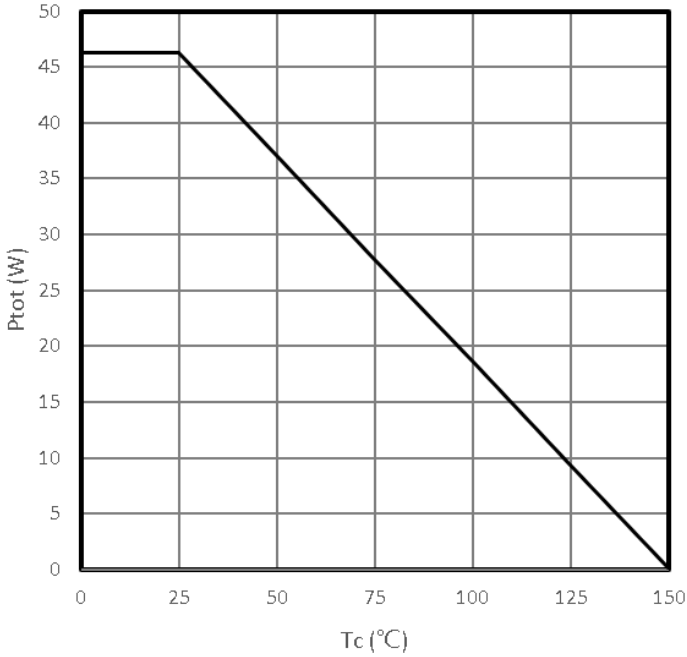


Typ. capacitances

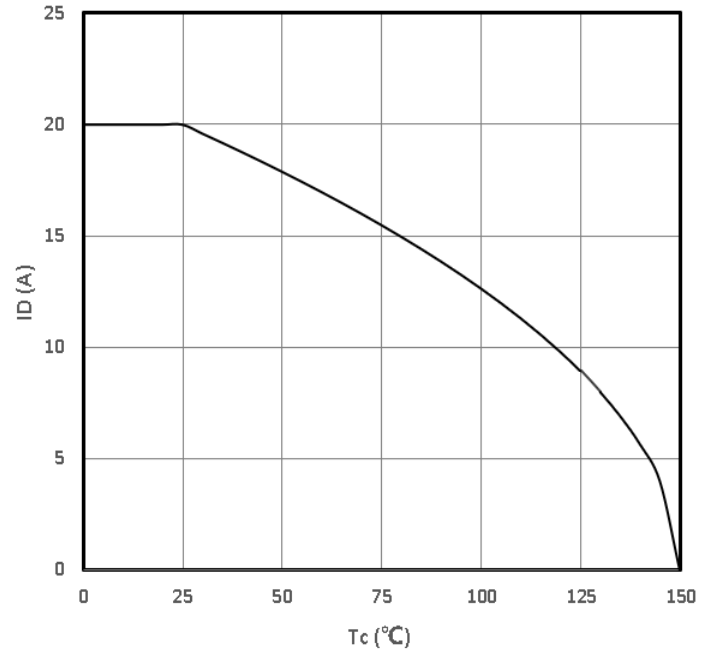
$C=f(V_{DS}); V_{GS}=0V; f=1MHz$



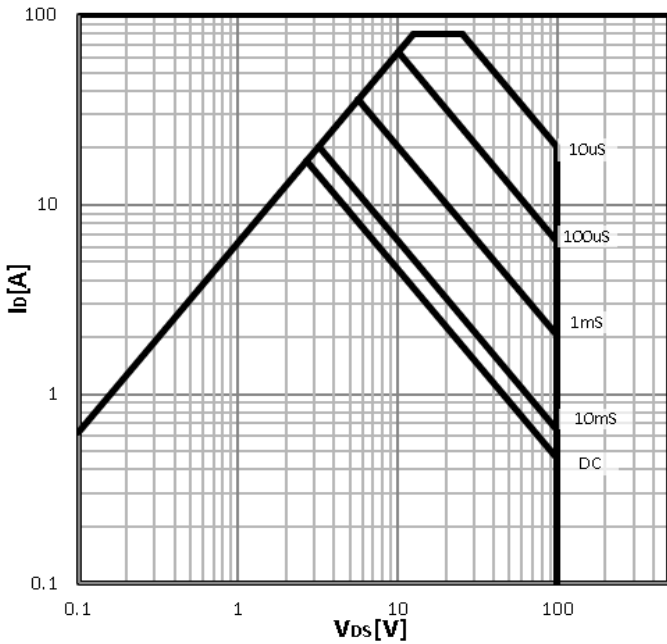
Power Dissipation
 $P_{tot}=f(T_c)$



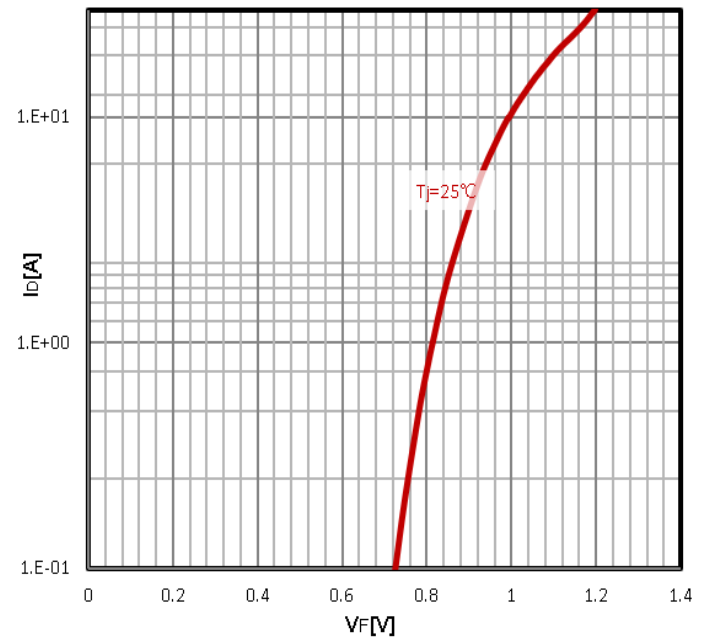
Maximum Drain Current
 $I_D=f(T_c)$



Safe operating area
 $I_D=f(V_{DS})$

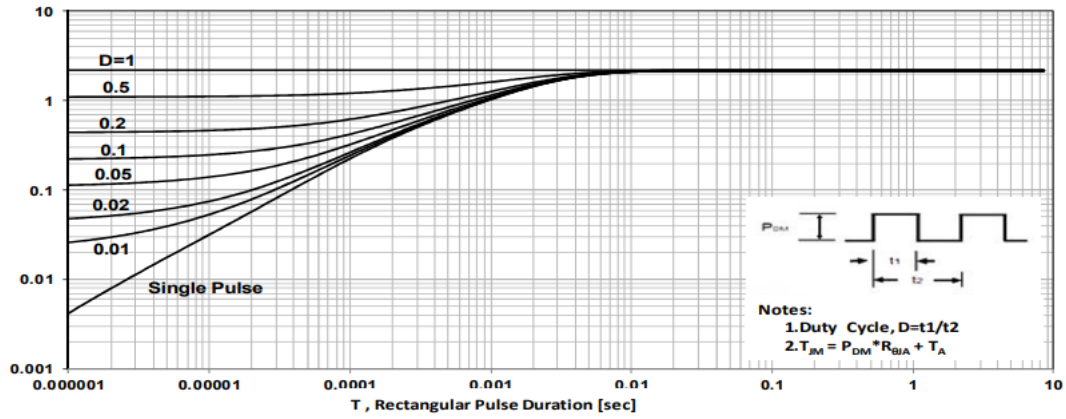


Body Diode Forward Voltage Variation
 $I_F=f(V_{GS})$

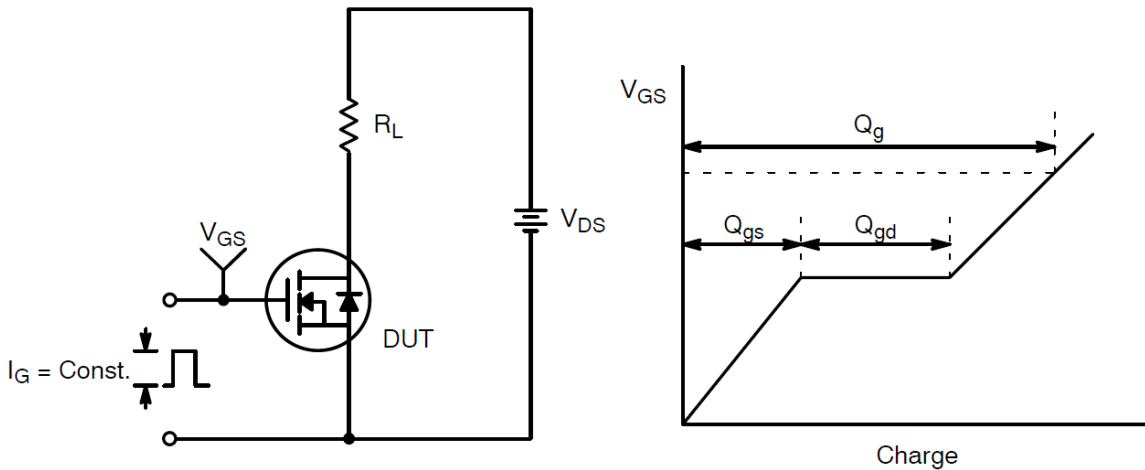


Max. transient thermal impedance

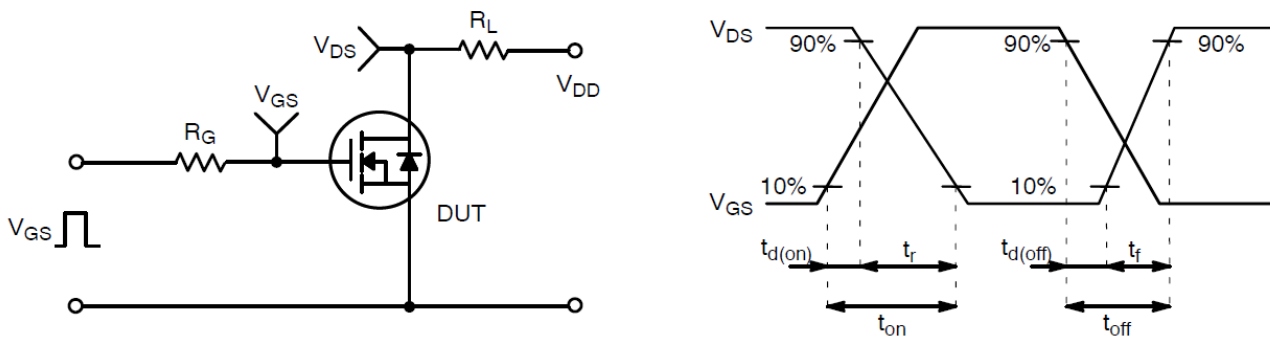
$$Z_{thJC}=f(t_p)$$



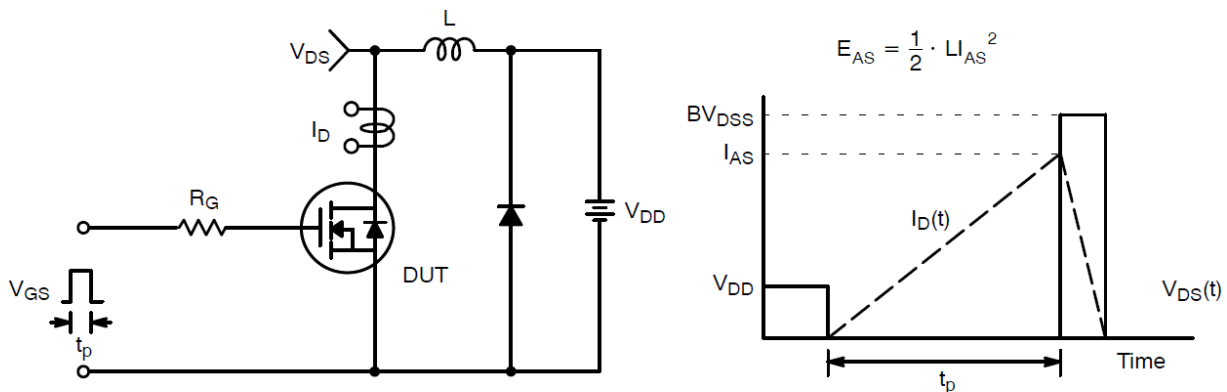
Test Circuit and Waveform:



Gate Charge Test Circuit & Waveform

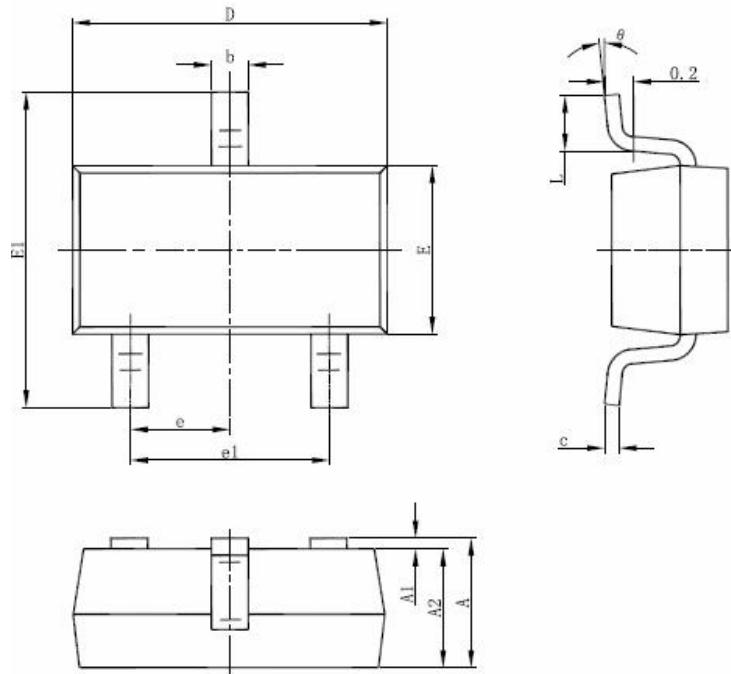


Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

SOT-23-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°